

**Abstract of the Disclosure**

A flip chip bonder including a substrate holding mechanism and a chip die bonder for bonding a semiconductor chip having a plurality of electrodes projecting from its front surface to a substrate held on the substrate holding means. The flip chip bonder includes a chuck table, a semiconductor chip take-out area and an electrode cutting area, a cutting mechanism having a cutting tool for cutting the plurality of electrodes projecting from the front surface of the semiconductor chip held on the chuck table and arranged in the electrode cutting area to make them uniform in height, a semiconductor chip take-in mechanism, and a semiconductor chip conveying mechanism.